

## N-MOSFET 100V 1.2mΩ 411A

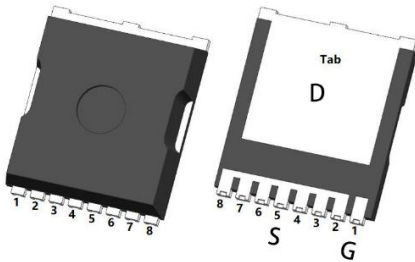
### Product Summary

- V<sub>DS</sub> 100V
- I<sub>D</sub> 411A
- R<sub>DS(ON)</sub> (at V<sub>GS</sub>=10V) < 1.6 mΩ (Typ: 1.2mΩ)

### Naming convention

M	G	V	0	1	2	N	1	0	A	N
Megain	B: PDFN3X3 C: PDFN5X6 P: TO220 H: TO263 S: SOP8 V: TOLL	R <sub>DS(ON)</sub> Typ. @V <sub>GS</sub> =10V	N: N P: P C: N+P D: N+N	15: 150V 12: 120V 10: 100V 06: 60V 04: 40V 03: 30V	A:V <sub>GS</sub> ±12 w/o A:V <sub>GS</sub> ±20	L:V <sub>th</sub> (1~2.5V) N:V <sub>th</sub> (2~4V)				

### Pin configuration



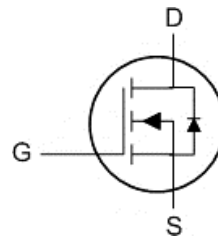
### Features

- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Low Thermal resistance
- Low R<sub>DS(ON)</sub> to minimize Conductive loss
- Advanced high cell density Trench technology

### Application

- MB/VGA Vcore
- SMPS 2<sup>nd</sup> Synchronous Rectifier
- POL application
- BLDC Motor driver

### Symbol



### Ordering Information

Order code	Package	Form	Quantity (PCS)	Marking
MGV012N10N	TOLL	Tape & Reel	2000/Tape & Reel	MGV012N10N

### Absolute Maximum Ratings

T<sub>C</sub>=25°C Unless Otherwise Noted.

Symbol	Parameter	Value	Units
V <sub>DS</sub>	Drain-Source Voltage	100	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current – Continuous <sup>1,6</sup> (T <sub>C</sub> =25°C)	411	A
	Drain Current – Continuous <sup>1,6</sup> (T <sub>C</sub> =100°C)	290	
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	1645	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	2121	mJ
I <sub>AS</sub>	Avalanche Current	206	A
P <sub>D</sub>	Total Power Dissipation <sup>4</sup> (T <sub>C</sub> =25°C)	600	W
P <sub>D</sub>	Total Power Dissipation <sup>4</sup> (T <sub>C</sub> =100°C)	300	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 175	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 175	°C

## ■ Thermal Characteristics

Symbol	Parameter	Max	Units
R <sub>θJA</sub>	Thermal Resistance Junction to Ambient <sup>1</sup>	40	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case <sup>1</sup>	0.25	°C/W

## ■ Electrical Characteristics

T<sub>J</sub>=25°C Unless Otherwise Noted.

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
B <sub>VDS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	100	-	-	V
R <sub>DS(ON)</sub>	Drain-Source On-state Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =50A	-	1.2	1.6	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	2.0	3.2	4.0	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =80V, V <sub>GS</sub> =0V T <sub>J</sub> =25°C	-	-	1	uA
		V <sub>DS</sub> =80V, V <sub>GS</sub> =0V T <sub>J</sub> =100°C	-	-	100	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =10A	-	44	-	S
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =50V, V <sub>GS</sub> =10V I <sub>D</sub> =50A	-	157	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	70	-	
Q <sub>gd</sub>	Gate-Drain Charge		-	62	-	
T <sub>d(ON)</sub>	Turn-on Delay Time	V <sub>DD</sub> =50V, V <sub>GS</sub> =10V, R <sub>G</sub> =4.5Ω, R <sub>L</sub> =1Ω, I <sub>D</sub> =50A	-	40	-	nS
T <sub>r</sub>	Turn-on Rise Time		-	122	-	
T <sub>d(OFF)</sub>	Turn-off Delay Time		-	144	-	
T <sub>f</sub>	Turn-off Fall Time		-	127	-	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V, f=1MHz	-	11074	-	pF
C <sub>oss</sub>	Output Capacitance		-	1736	-	
C <sub>rss</sub>	Reverse Transfer Capacitance		-	176	-	

### Diode Characteristics

I <sub>S</sub>	Continuous Source Current <sup>1,5,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	-	-	411	A
I <sub>SM</sub>	Pulsed Source Current <sup>2,5</sup>		-	-	823	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	I <sub>S</sub> =50A, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	-	-	1.3	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =50A, di/dt=100A/us,	-	120	-	nS
Q <sub>rr</sub>	Reverse Recovery Charge	T <sub>J</sub> =25°C	-	347	-	nC

Note :

- The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%.
- The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=50V, V<sub>GS</sub>=10V, L=0.1mH, I<sub>AS</sub>=206A.
- The power dissipation is limited by 175°C junction temperature.
- The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications , should be limited by total power dissipation.

■ Typical Characteristics

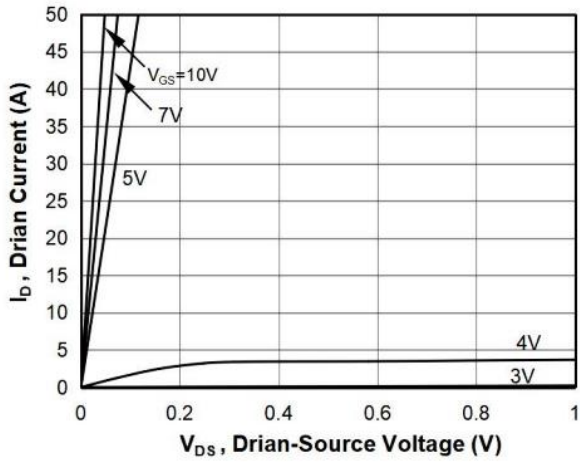


Fig.1 Typical Output Characteristics

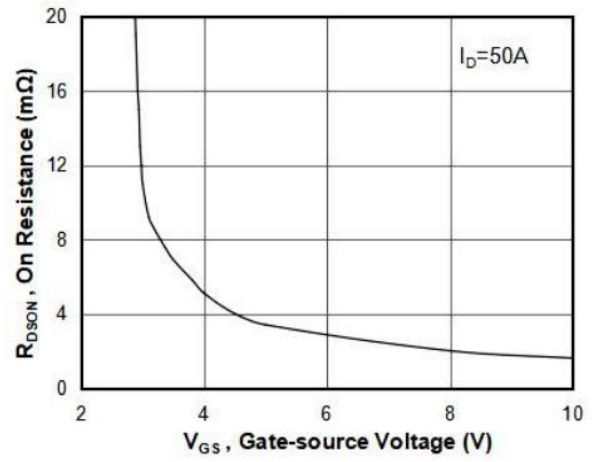


Fig.2 On-Resistance v.s Gate-Source

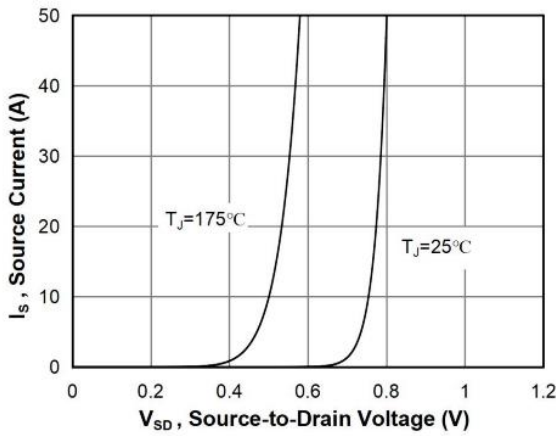


Fig.3 Source Drain Forward Characteristics

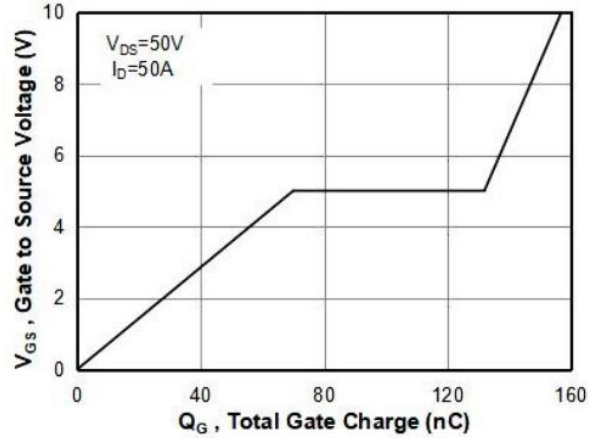


Fig.4 Gate-Charge Characteristics

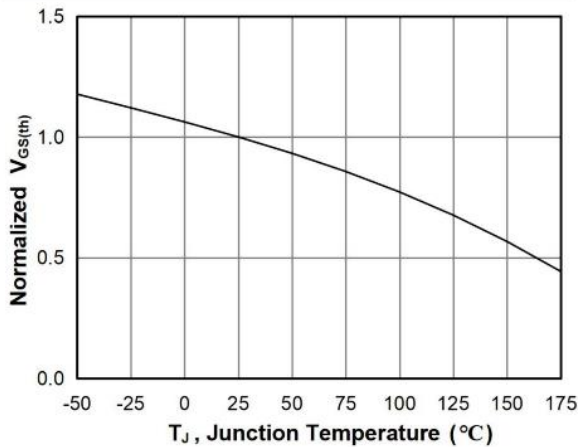


Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$

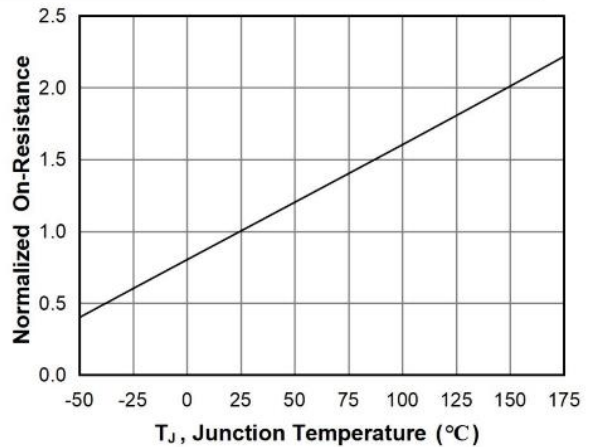


Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$

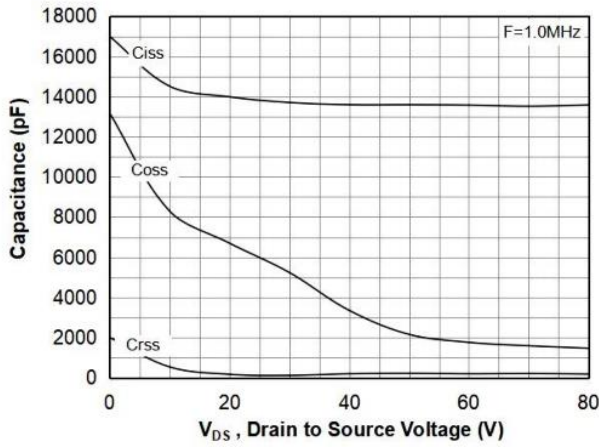


Fig.7 Capacitance

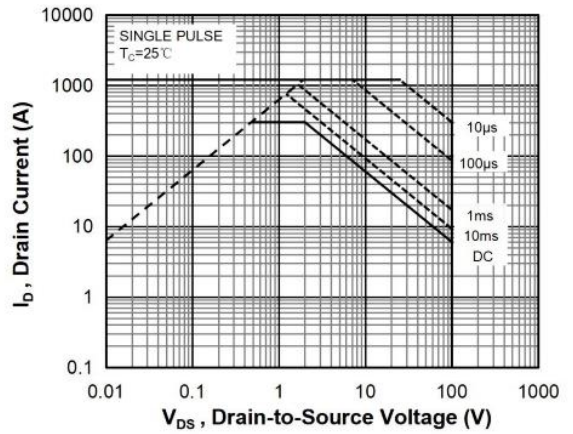


Fig.8 Safe Operating Area

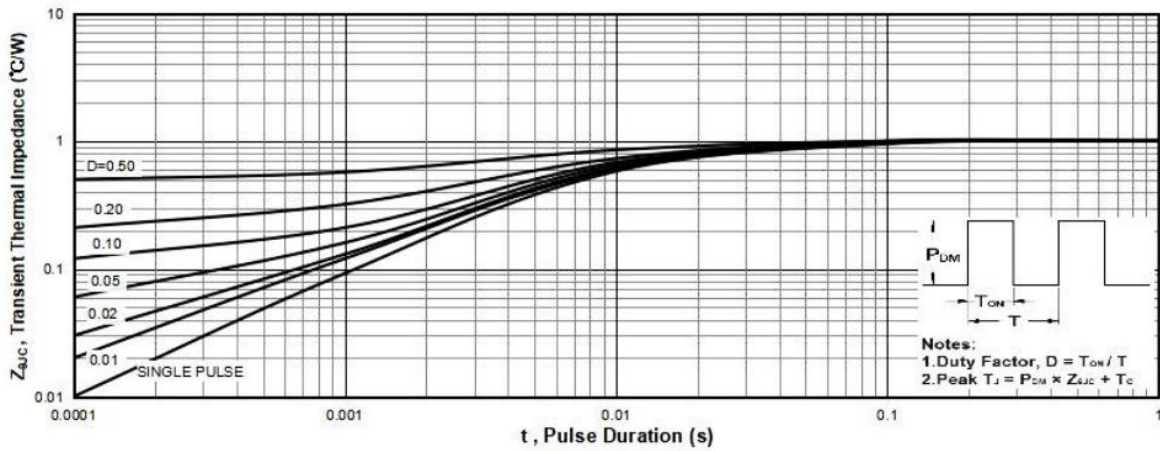


Fig.9 Normalized Maximum Transient Thermal Impedance

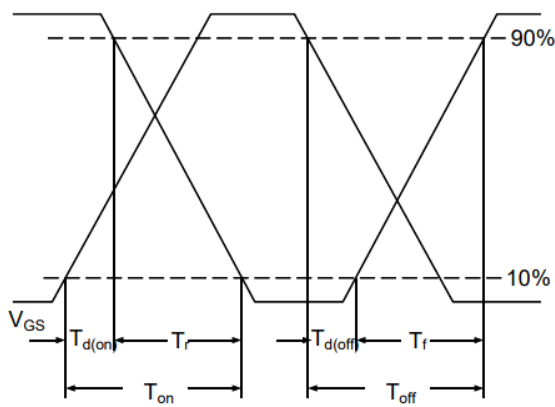


Fig.10 Switching Time Waveform

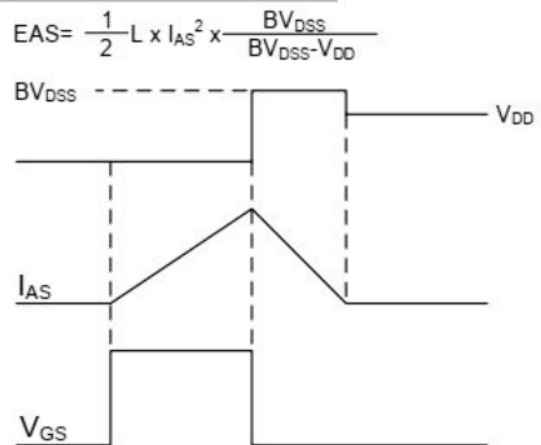
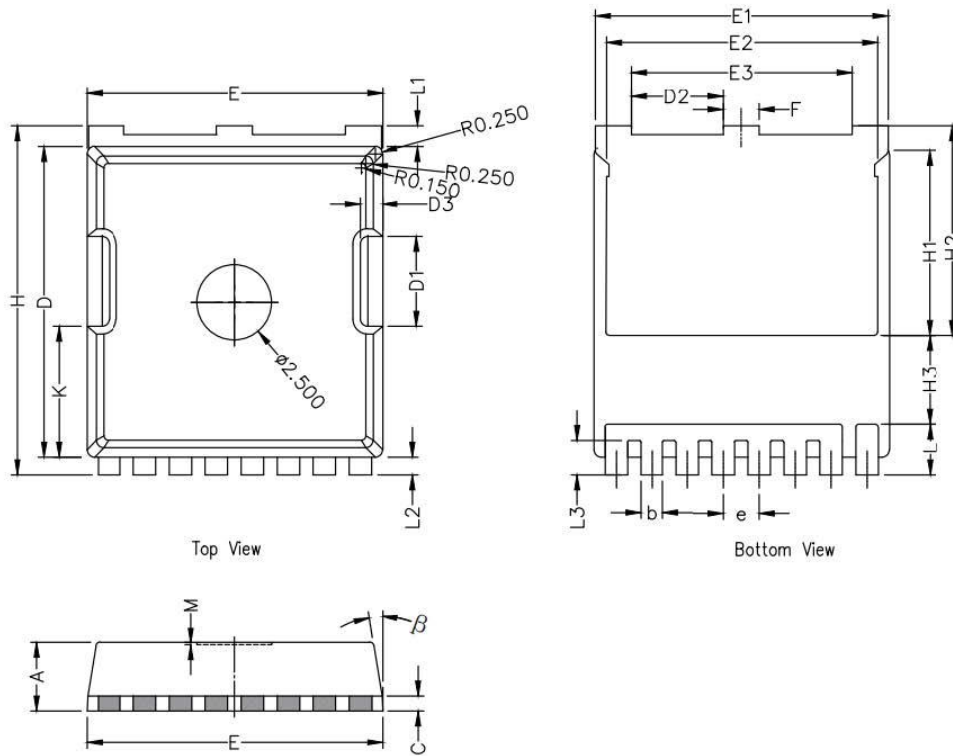


Fig.11 Unclamped Inductive Waveform

## ■ Package size

Unit: mm.

TOLL:



Symbols	Millimeters		
	MIN.	NOM.	MAX.
A	2.20	2.30	2.40
b	0.65	0.75	0.85
C	0.508 REF		
D	10.25	10.40	10.55
D1	2.85	3.00	3.15
D2	2.95	3.10	3.25
D3	0.75 REF		
E	9.75	9.90	10.05
E1	9.65	9.80	9.95
E2	8.95	9.10	9.25
E3	7.25	7.40	7.55
e	1.20 BSC		
F	1.05	1.20	1.35
H	11.55	11.70	11.85
H1	6.03	6.18	6.33
H2	6.85	7.00	7.15
H3	3.00 BSC		
L	1.55	1.70	1.85
L1	0.55	0.70	0.85
L2	0.45	0.60	0.75
L3	1.00	1.15	1.30
M	0.08 REF		
$\beta$	8°	10°	12°
K	4.25	4.40	4.55